

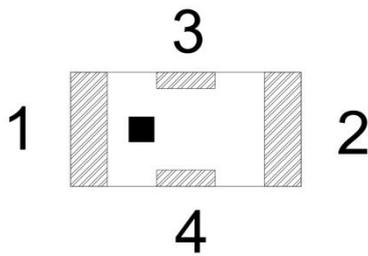
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

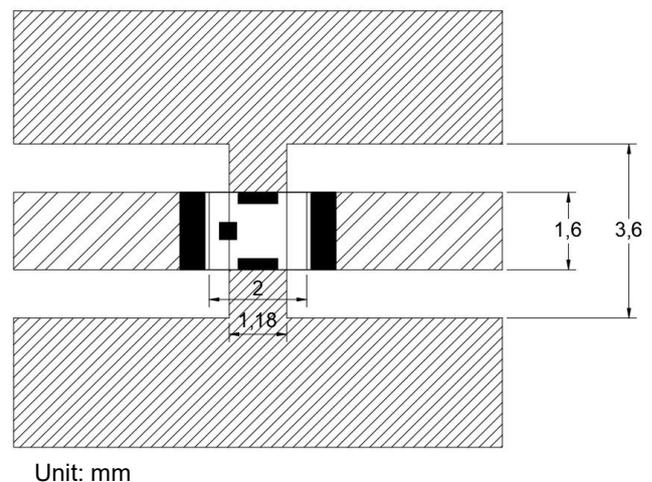
NO.	Parameter	SPC
1	Frequency (MHz)	1300~1950
2	Insertion Loss (dB)@25°C	≤1.5
3	VSWR(In BW)	≤2.0
4	Ripple (dB)	≤1.0 dB
5	Attenuation	DC~1000MHz
		3250MHz
6	In/Output Impedance (Ω)	50
7	Input Power	10W
Operating & Storage Condition (Component)		
Operation Temperature Range: -40°C ~ +85°C		
Storage Temperature Range: -40°C~ +85°C		
Storage Condition before Soldering (Included packaging material)		
Storage Temperature Range: +5 ~ +40 °C		
Humidity: 30 to 70% relative humidity		

Construction

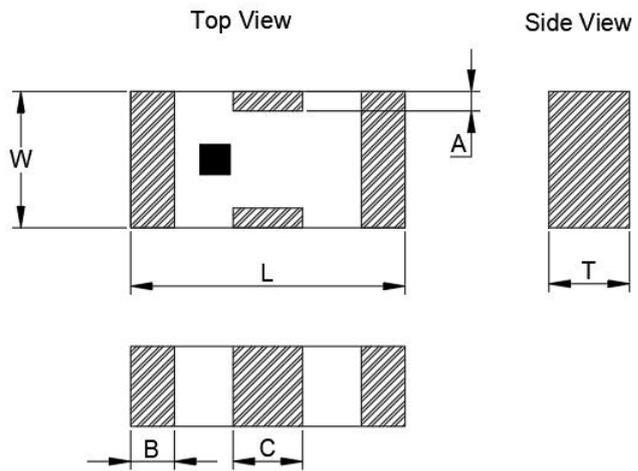


PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

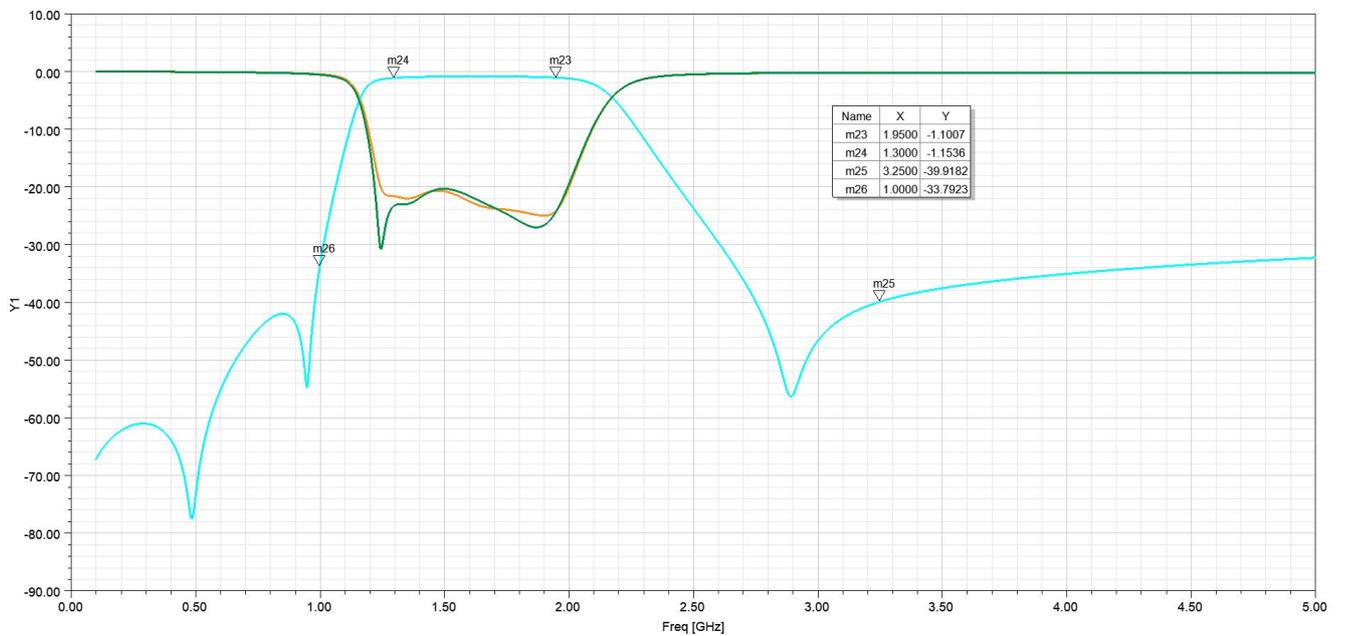
Mounting Considerations



Dimensions

Figure	Symbol	Dimension (mm)
	L	3.20 ± 0.20
	W	1.60 ± 0.20
	T	0.94 ± 0.20
	A	0.23 ± 0.10
	B	0.51 ± 0.10
	C	0.81 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.